

**Product/ Process Change Notification** 

Froducti Frocess Change Nothication				
1. PCN No.:		QPCN12024		
2. Subject:		Bonding wire material change at SOD-323 (Switching, Zener & SKY) SMD Diode		
3. To:		Refer to involved customer list		
4. Issued by:		Owen Wang		
5. Issue date:		3-Dec-2012		
6. Proposed first ship date for change:		4-Mar-2013		
7. Affected Product Identification				
Switching Diode & Array, Zener Diode & Array, and Schottky Diode & Array, SOD-323 package More details please see TSC involved P/N list.				
8. Change Description : (OLD Vs. NEW Comparison)				
Old:		New:		
➤ Gold bonding wire.		➤ Copper bonding wire.		
9. Reason for Change:				
Follow the trend of common process in the market.				
10. Anticipated Impact: (form, fit, functi	ion, qual	ity or reliability)		
1. Product outline: N	No change			
_	Bonding wire material change			
•	No change			
,	No change No change			
	No change No change			
	_	v date code		
11.Qualification plan/result:				
<ul><li>Comparison report see attached</li><li>PPAP is available on demand</li></ul>				
12. Sample availability Date:		3-Dec-2012		
13. Tentative implementation date:		3-Jan-2013		
14. Remarks				
15. Customer feedback required latest: (should we receive no feedback; the change will be deemed as accepted!)		3-Jan-2013		
16. Approved by:		Quayer Chen		



## **Product/ Process Change Notification** Customer Approval Form\_QPCN12024

(Please tick the field what is valid for you!)				
We agree with this proposed change and its schedule.				
We have object	tions			
■ We need more				
We need samp	le:			
Company:				
Name:				
Address:				
Signature:		Date:		